TRADEMARK ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE BY SECURED PARTY

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
BMO Harris Financing, Inc.		03/02/2012	INC. ASSOCIATION:

RECEIVING PARTY DATA

Name:	Raybestos Powertrain, LLC
Street Address:	609 East Chaney St.
City:	Sullivan
State/Country:	INDIANA
Postal Code:	47882
Entity Type:	LIMITED LIABILITY COMPANY: DELAWARE

PROPERTY NUMBERS Total: 9

Property Type	Number	Word Mark
Registration Number:	1673388	PERFORMANCE THROUGH TECHNOLOGY
Registration Number:	1678426	BLUE PLATE SPECIAL
Registration Number:	1739690	RAY USA
Registration Number:	1738236	RAY-FLEX
Registration Number:	1822121	CLUTCH-PACK
Registration Number:	2891768	X-32
Registration Number:	2952645	SW CARBON
Registration Number:	2957628	TAKES HEAT WITHOUT CONING ZPAK
Registration Number:	3754122	ALLOMATIC

CH $240.00 1673388

CORRESPONDENCE DATA

Fax Number: 2163485474

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.

Phone: 216-348-5400
Email: ip@mcdonaldhopkins.com

Correspondent Name: McDonald Hopkins LLC
Address Line 1: 600 Superior Avenue
Address Line 2: Suite 2100
Address Line 4: Cleveland, OHIO 44114

ATTORNEY DOCKET NUMBER:	FRICTION
NAME OF SUBMITTER:	Todd A. Benni
Signature:	/Todd A. Benni/
Date:	04/23/2012

Total Attachments: 4
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TERMINATION AND RELEASE OF SECURITY INTEREST IN TRADEMARKS AND PATENTS

This **TERMINATION AND RELEASE OF SECURITY INTEREST TRADEMARKS AND PATENTS**, dated as of March 2, 2012 ("Release"), is made by BMO Harris Financing, Inc. (formerly known as BMO Capital Markets Financing, Inc.), a Delaware corporation as Lender, and Bank of Montreal, a Canadian charted bank (the "Grantees") in favor of Raybestos Powertrain, LLC a Delaware limited liability company (the "Grantor").

WHEREAS, Grantees and Grantor, among others entered in that certain Security Agreement (as the same may have been amended from time to time, the "Security Agreement");

WHEREAS, pursuant to the Grant of Security Interest in Intellectual Property by and among the Grantor and the Grantees dated as of December 28, 2009 (the "IP Security Agreement") Grantor granted to Grantees a security interest in the Grantor's right, title and interest in and to at least: (i) the trademarks, trademark registrations, trademark applications and any and all goodwill associated therewith (the "Marks") set forth on Schedule A attached hereto; and (ii) the patents and patent application (the "Patents") set forth on Schedule B attached hereto (collectively; the "Trademark and Patent Collateral") and

WHEREAS, the IP Security Agreement was recorded at the United States Patent and Trademark Office ("USPTO") as indicated in the attached Schedules;

NOW THEREFORE, in consideration of the mutual promises and undertakings set forth herein and for other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, and with the intention of being legally bound hereby, Grantees and Grantor (the "parties") agree as follows:

SECTION 1. Defined Terms. All capitalized terms used herein but not otherwise defined herein have the meanings given to them in the IP Security Agreement.

SECTION 2. Termination and Release. Grantees hereby:

(a) terminate, cancel, discharge, and release the mortgage, pledge, and hypothecation, collateral assignment, and lien on and security interest in and to the Trademark and Patent Collateral (including without limitation those Trademarks and Patents listed on Schedules A and B hereto); and

(b) authorizes the recordation of this Release with the USPTO.

SECTION 3. Any signatures delivered by a party by facsimile transmission or by e-mail transmission for this Termination and Release of Security Interest in Trademarks and Patents shall be deemed an original signature hereto.

IN WITNESS WHEREOF, the Grantees have caused this Termination and Release of Security Interest in the Trademarks and Patents to be duly executed as of the date first set forth above.

Grantees: BMO Harris Financing, Inc. (as Lender)

By: Denise Sidlo
Name: DENISE SIDLO
Title: Director

Bank of Montreal

By: Denise Sidlo
Name: DENISE SIDLO
Title: Director

Schedule A

Registered Marks

Mark	Registration No.	Secured Party	Reel	Frame
PERFORMANCE THROUGH TECHNOLOGY	1673388	Raybestos Powertrain, LLC	4122	0072
BLUE PLATE SPECIAL	1678426	Raybestos Powertrain, LLC	4122	0072
RAY USA	1739690	Raybestos Powertrain, LLC	4122	0072
RAY-FLEX	1738236	Raybestos Powertrain, LLC	4122	0072
CLUTCH-PACK	1822121	Raybestos Powertrain, LLC	4122	0072
X-32	2891768	Raybestos Powertrain, LLC	4122	0072
SW CARBON	2952645	Raybestos Powertrain, LLC	4122	0072
TAKES HEAT WITHOUT CONING ZPAK	2957628	Raybestos Powertrain, LLC	4122	0072
ALLOMATIC	3754122	Raybestos Powertrain, LLC	4122	0072

Schedule B

Issued Patents

Patent No.	Title	Assignee	Reel	Frame
6852020	Polishing Pad for use in Chemical – Mechanical Planarization of Semiconductor Wafers and Method of Making Same	Raybestos Powertrain, LLC	023708	0269
6863774	Polishing Pad for use in Chemical – Mechanical Planarization of Semiconductor Wafers and Method of Making Same	Raybestos Powertrain, LLC	023708	0269
6875077	Polishing Pad for use in Chemical – Mechanical Planarization of Semiconductor Wafers and Method of Making Same	Raybestos Powertrain, LLC	023708	0269
6899610	Retaining Ring with Wear Pad for use in Chemical Mechanical Planarization	Raybestos Powertrain, LLC	023708	0269
6945846	Polishing Pad for use in Chemical/Mechanical Planarization of Semiconductor Wafers Having a Transparent Window for End-Point Determination and Method of Making	Raybestos Powertrain, LLC	023708	0269
6964601	Method for Securing a Polishing Pad to a Platen for use in Chemical-Mechanical Polishing of Wafers	Raybestos Powertrain, LLC	023708	0269
6979256	Retaining Ring with Wear Pad for use in Chemical Mechanical Planarization	Raybestos Powertrain, LLC	023708	0269
7025668	Gradient Polishing Pad Made from Paper-Making Fibers for use in Chemical/Mechanical Planarization Wafers	Raybestos Powertrain, LLC	023708	0269
7037184	Polishing Pad for use in Chemical-Mechanical Planarization of Semiconductor Wafers and Method of Making Same	Raybestos Powertrain, LLC	023708	0269